

INCH-POUND

The documentation and process conversion measures necessary to comply with this revision shall be completed by 29 July 2019.

MIL-PRF-19500/291Y
27 March 2019
SUPERSEDING
MIL-PRF-19500/291W
17 May 2016

PERFORMANCE SPECIFICATION SHEET

TRANSISTOR, PNP, SILICON, SWITCHING, DEVICE TYPES 2N2906A AND 2N2907A,
ENCAPSULATED (THROUGH HOLE AND SURFACE MOUNT PACKAGES) AND UNENCAPSULATED,
RADIATION HARDNESS ASSURANCE,
QUALITY LEVELS JAN, JANTX, JANTXV, JANS, JANHC, AND JANKC

This specification is approved for use by all Departments and Agencies of the Department of Defense.

The requirements for acquiring the product described herein shall consist of this specification sheet and [MIL-PRF-19500](#).

1. SCOPE

1.1 Scope. This specification covers the performance requirements for PNP, silicon, switching transistors. Four levels of product assurance (JAN, JANTX, JANTXV and JANS) are provided for each encapsulated device type as specified in [MIL-PRF-19500](#) and two levels of product assurance (JANHC and JANKC) are provided for each unencapsulated device type. Provisions for radiation hardness assurance (RHA) to eight radiation levels is provided for quality levels JANTXV, JANS, JANHC, and JANKC.

1.2 Physical dimensions.

1.2.1 Package outlines. The device package outlines for the encapsulated device types are as follows: Three terminal round metal can TO-206AA (formerly TO-18) in accordance with [figure 1](#), four terminal surface mount device (SMD) package in accordance with [figure 2](#), and three or four terminal SMD package in accordance with [figure 3](#).

1.2.2 Unencapsulated die. The dimensions and topography for JANHC and JANKC unencapsulated die are as follows: The B version die (JANHCB and JANKCB) is in accordance with [figure 4](#) and the D version die (JANHCD and JANKCD) is in accordance with [figure 5](#).

1.3 Maximum ratings. Unless otherwise specified $T_A = +25^\circ\text{C}$.

| Types | I_C | V_{CBO} | V_{EBO} | V_{CEO} | T_J and T_{STG} |
|-------------|--------------|-------------|-------------|-------------|---------------------|
| | <u>mA dc</u> | <u>V dc</u> | <u>V dc</u> | <u>V dc</u> | <u>°C</u> |
| All devices | -600 | -60 | -5 | -60 | -65 to +200 |

Comments, suggestions, or questions on this document should be addressed to DLA Land and Maritime, ATTN: VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to Semiconductor@dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.dla.mil>.

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